

Full Bridge DC Motor Driver

Features and Benefits

- Supply voltage, V_{BB}, 36 V maximum
- Maximum DC current 3 A continuous, 6 A pulsed (1 kHz, duty cycle < 1%, pulse width < 10 μs)
- $R_{DS(on)} = 300 \text{ m}\Omega \text{ maximum, at } T_J = 125^{\circ}C$
- Operation modes: forward, reverse, brake (high- or lowside freewheeling current circulation)
- Output disable pin (DI pin)
- Protections:
- Overvoltage protection (OVP), 36 V minimum
- Overcurrent protection (OCP), 3 A typical
- Overcurrent limitation (OCL), 6 A typical
- Externally adjustable delay timer to halt OCL
- Thermal shutdown protection (TSD), 151°C minimum
- ^o Undervoltage lockout on V_{BB} (UVLO), 4.2 V minimum
- Open load detection at startup
- Diagnosis output linked to OVP, OCP, TSD, UVLO, and open load detection, at startup and in operation

Package: 16 pin HSOP with exposed thermal pad and tabs



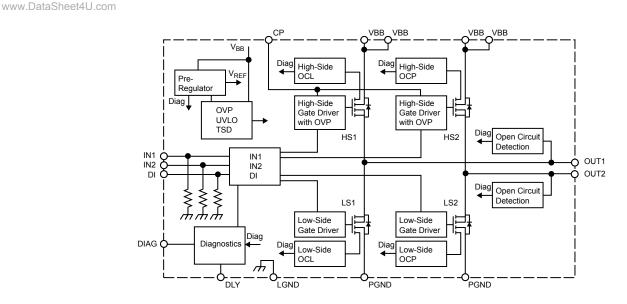
Not to scale

Description

The SPF7302 is a fully protected, single chip full-bridge driver IC for DC brush motor applications. The various protection circuits integrated are: overvoltage protection (OVP); overcurrent protection (OCP) with latch, which is adapted to the DMOSFETs in each full bridge; undervoltage lockout (UVLO); open load detection; and overcurrent limitation.

The package is a thermally enhanced 16-pin HSOP power package with an exposed thermal pad on the bottom side of the package.

Functional Block Diagram



Full Bridge DC Motor Driver

Selection Guide

Part Number	Package	Packing
SPF7302	Thermally enhanced surface mount (HSOP), 16-pin	Minimum quantity 1400 pieces

Absolute Maximum Ratings at T_A = 25°C

Characteristic	Symbol	Notes	Rating	Unit
Supply Voltage	V _{BB}		-0.3 to 36	V
IN1, IN2, DI, and DLY Pin Input Voltage	V _x		-0.3 to 6	V
Output Ourropt	Ι _Ο		±3	A
Output Current	I _{Opeak}	Continuous: 1 kHz, duty cycle <1%; pulse: < 10 µs	±6	А
DIAG Pin Output Voltage	V _{DIAG}		-0.3 to 6	V
DIAG Pin Input Current	I _{DIAG}	DIAG pin sink current	-2	mA
CP Pin Voltage	V _{CP}		-0.3 to 36	V
	P _{D1}	With infinite heatsink	39	
Power Dissipation	P _{D2}	Mounted on glass epoxy PCB, 50 mm×74 mm×1.6 mm; 0.5 oz copper (18 µm thick) exposed copper area	4	W
Junction Temperature	TJ		-40 to 150	°C
Operating Ambient Temperature	T _A		-40 to 105	°C
Storage Temperature	T _{stg}		40 to 150	°C
Thermal Resistance, Junction to Case $R_{\theta JC}$		Mounted on glass epoxy PCB, 50 mm × 74 mm × 1.6 mm;	3.2	°C/W
Thermal Resistance, Junction to Ambient	R _{θJA}	0.5 oz copper (18 µm thick) exposed copper area	31	°C/W

Terminal List Table

www.DateSheet41 Diagram LGND 1 16 LGND Ο IN2 2 15 DIAG IN1 3 14 DLY 13 CP DI 4 VBB 5 12 VBB 11 VBB VBB 6 10 OUT1 OUT2 7 PGND 8 9 PGND

Number	Name	Description
1	LGND	Logic GND
2	IN2	Input pin 2
3	IN1	Input pin 1
4	DI	Disable pin
5	VBB	Supply input voltage
6	VBB	Supply input voltage
7	OUT2	Output 2
8	PGND	Power GND
9	PGND	Power GND
10	OUT1	Output 1
11	VBB	Supply input voltage
12	VBB	Supply input voltage
13	CP	Charge pump capacitor pin
14	DLY	Overcurrent limitation delay setting input pin
15	DIAG	Diagnostics output pin
16	LGND	Logic GND

All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature, T_A, of 25°C, unless otherwise stated.





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ELECTRICAL CHARACTERISTICS¹ valid at $T_J = -30^{\circ}C$ to $125^{\circ}C$, $V_{BB} = 14$ V, $V_{DI} = 5$ V, $C_{CP} = 47$ nF, $R_{DIAG} = 5.1$ k Ω , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Supply Voltage	V _{BB}		6	-	18	V
	I _{leakHS}		-1	_	_	mA
OUTx Pin Leakage Current	I _{leakLS}		_	-	1	mA
	R _{DS(ON_1H}	I _{OUT} = 1 A	_	_	300	mΩ
	R _{DS(ON)_2H}	I _{OUT} = 3 A	_	_	300	mΩ
DMOSFET On Resistance	R _{DS(ON)_1L}	I _{OUT} = 1 A	_	-	300	mΩ
	R _{DS(ON)_2L}	I _{OUT} = 3 A	_	_	300	mΩ
	V _{F_H1}	I _{OUT1} = 1 A	_	1.0	2.0	V
	V _{F_H2}	I _{OUT2} = 1 A	_	1.0	2.0	V
DMOSFET Body Diode Forward Voltage	V _{F_L1}	I _{OUT1} = -1 A	_	1.0	2.0	V
	V _{F_L2}	I _{OUT2} = -1 A	_	1.0	2.0	V
Quiescent Current	I _{BB}		_	7	_	mA
	I _{OCL_H1}		2.0	3.0	4.5	А
Overcurrent Limit (OCL)	I _{OCL_H2}	$T_J = -40^{\circ}$ C to 150°C, $I_{OCL} < I_{OCP}$; guaranteed by	2.0	3.0	4.5	А
	I _{OCL_L1}	design	2.0	3.0	4.5	А
	I _{OCL_L2}		2.0	3.0	4.5	А
Overcurrent Protection (OCP)	I _{OCP_H1}		4.5	6.0	8.0	А
	I _{OCP_H2}	$T_J = -40^{\circ}$ C to 150°C, $I_{OCL} < I_{OCP}$; guaranteed by	4.5	6.0	8.0	А
	I _{OCP_L1}	design	4.5	6.0	8.0	А
	I _{OCP_L2}		4.5	6.0	8.0	А
	V _{x_H}		3.0	_	5.3	V
IN1, IN2, DI, and DLY Pin Input Voltage	V _{x_L}		-0.3	_	1.5	V
w.DataSheet4U.com	I _{x_H}	V _{DLY} = 5 V	_	100	200	μA
IN1, IN2, DI, and DLY Pin Input Current	I _{x_L}	V _{DLY} = 0 V	-1	_	1	μA
	V _{DIAG_H}	$V_{CC} = 5 V$	4.0	_	_	V
IAG Pin Output Voltage	V _{DIAG_L}	I _{sink} = 2 mA	_	_	0.4	V
	I _{DIAG H}	V _{CC} = 5 V, DIAG pin source current	-250	_	_	μA
DIAG Pin Output Current	I _{DIAG_L}	V_{CC} = 5 V, DIAG pin sink current, V_{DIAG} = 2 V	_	_	3	mA
	t _{INx_ON}	Delay from $V_{INx} = 2 V \rightarrow V_{OUTx} \times 0.2$		7	15	μs
N1 and IN2 Pin Input Propagation Time	t _{INx_OFF}	Delay from V_{INx} = 1.5 V \rightarrow V _{OUTx} × 0.8		7	15	μs
Output Rise Time	t _{rx}	Delay from $V_{OUTx} = 20\% \rightarrow 80\%$ points, at $I_{OUTx} = 1$ A	_	0.5	2	μs
Output Fall Time	t _{fx}	Delay from V _{OUTx} = 20%→80% points, at I _{OUTx} =1 A	_	0.5	2	μs

Continued on the next page ...





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ELECTRICAL CHARACTERISTICS¹ (continued) valid at $T_J = -30^{\circ}$ C to 125°C, $V_{BB} = 14$ V, $V_{DI} = 5$ V, $C_{CP} = 47$ nF, R_{DIAG} = 5.1 k Ω , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
DLY Pin Threshold Voltage	V _{DLY(th)}	Overcurrent limitation (OCL) activating voltage	1.4	1.6	1.8	V
DLY Pin Sourcing Current ²	I _{DLY}		15	30	60	μA
UVLO Releasing Voltage	V _{UVLO_OFF}		-	-	5.2	V
UVLO Activating Voltage	V _{UVLO_ON}		4.2	-	-	V
UVLO Hysteresis	V _{UVLOhys}		-	0.2	-	V
OVP Protection Activating Voltage	V _{OVP_ON}		36	-	42	V
OVP Protection Releasing Voltage	V _{OVP_OFF}		32	-	38	V
OVP Hysteresis	V _{OVPhys}		-	5	-	V
Thermal Shutdown Activating Temperature ³	T _{TSD_ON}	Starts at 165°C typical; guaranteed by design	151	165	-	°C
Thermal Shutdown Releasing Temperature ³	T _{TSD_OFF}	Guaranteed by design	136	150	_	°C
Thermal Shutdown Hysteresis ³	T _{TSDhys}	Guaranteed by design	-	15	-	°C

¹The parameters at $T_J = -40^{\circ}$ C to 150°C are specified by design. The actual production tests are done at 25°C and 125°C.

²The individual overcurrent limitation of each DMOSFET is masked during the delay period. Therefore, ensure proper thermal design for dissipating transient temperature increase caused by current during this period.

³TSD (thermal shutdown protection starts at 165°C typical, and it is specified by design.

Motor Control Truth Table¹

Reference	Status	Input			Output			DMOSFET status			
Number	Status		IN1	IN2	OUT1	OUT2	DIAG	HS1	LS1	HS2	LS2
1	Forward rotation ²	Н	Н	L	Н	L	Н	ON	OFF	OFF	ON
w.DataSheet4	Reverse rotation ²	Н	L	Н	L	Н	н	OFF	ON	ON	OFF
3	Low-side freewheeling	Н	L	L	L	L	н	OFF	ON	OFF	ON
4	High-side freewheeling	Н	Н	Н	н	Н	н	ON	OFF	ON	OFF
5	Output disabled	L	Х	Х	Z	Z	Н	OFF	OFF	OFF	OFF
6	Overcurrent limitation (OCL) active (HS1)	Н	Н	Х	Н	Х	Н	ON	OFF	Х	Х
7	Overcurrent limitation (OCL) active (HS2)	Н	Х	Н	X	Н	н	Х	Х	ON	OFF
8	Overcurrent limitation (OCL) active (LS1)	Н	L	Х	L	Х	н	OFF	ON	Х	Х
9	Overcurrent limitation (OCL) active (LS2)	Н	Х	L	X	L	н	Х	Х	OFF	ON
10	Overcurrent protection with latch (OCP) active (HS1)	Н	Н	Х	Z	Z	L	OFF	OFF	OFF	OFF
11	Overcurrent protection with latch (OCP) active (HS2)	Н	Х	Н	Z	Z	L	OFF	OFF	OFF	OFF
12	Overcurrent protection with latch (OCP) active (LS1)	Н	L	Х	Z	Z	L	OFF	OFF	OFF	OFF
13	Overcurrent protection with latch (OCP) active (LS2)	Н	Х	L	Z	Z	L	OFF	OFF	OFF	OFF
14	Undervoltage lockout (UVLO) protection active	Х	Х	Х	Z	Z	L	OFF	OFF	OFF	OFF
15	Overvoltage protection (OVP) active	Х	Х	Х	X	Х	L	Х	Х	Х	Х
16	Open load detected at startup	L	Х	Х	X	Х	L	OFF	OFF	OFF	OFF
17	Open load detected in operation	Н	Х	Х	X	Х	L	Х	Х	Х	Х
18	Thermal shutdown protection (TSD) active	Х	Х	Х	Z	Z	L	OFF	OFF	OFF	OFF

¹X is "don't care," Z is high impedance.

2"Forward" and "reverse" only indicate opposite relative direction.





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Switching Operation Timing Charts

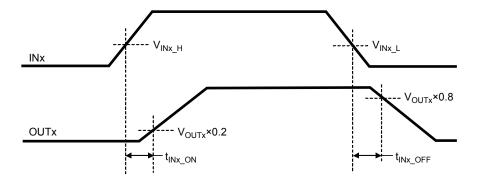


Figure 1. Output Delay Time

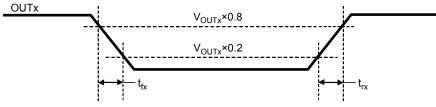


Figure 2. Output Switching Time

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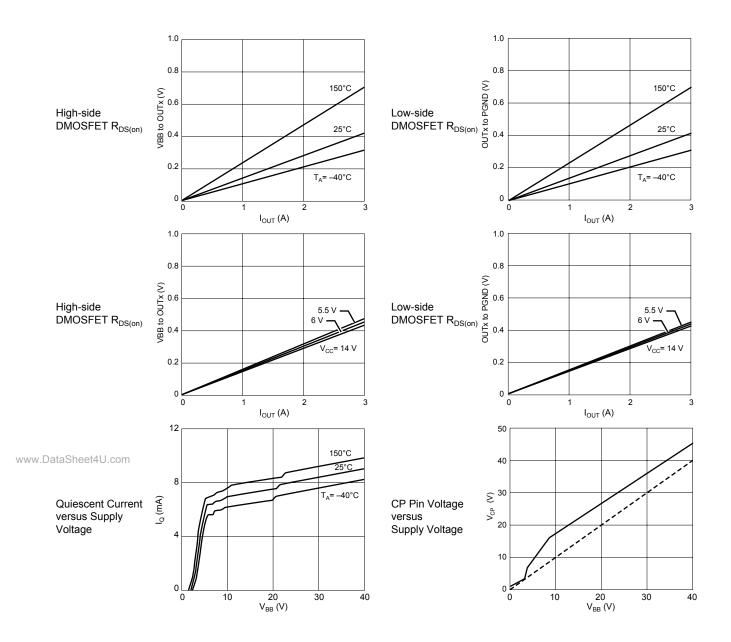




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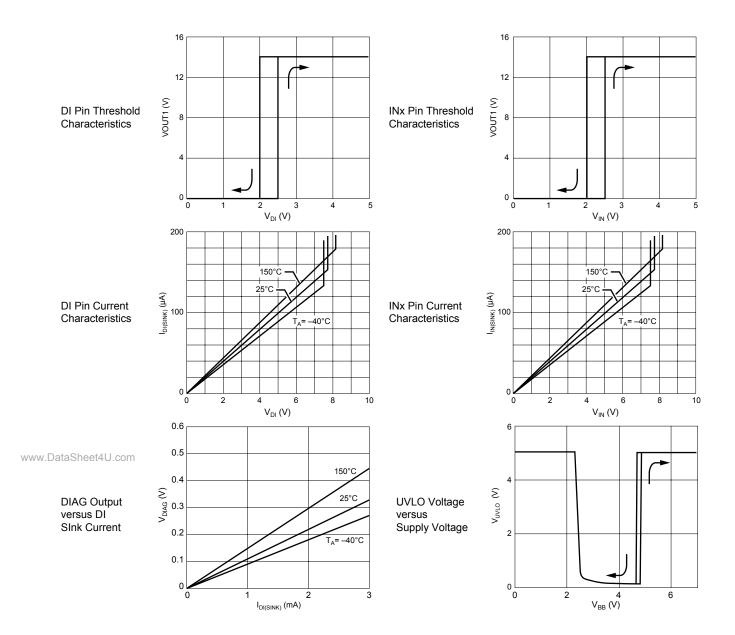
 T_A = 25°C unless otherwise specified







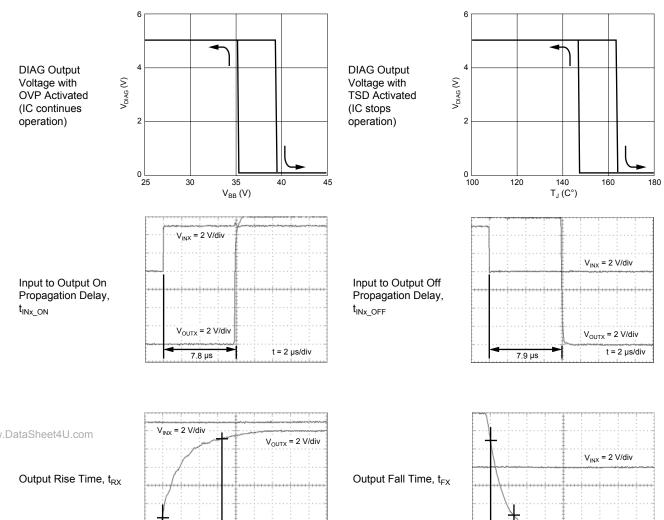
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t = 50 ns/div



	7
an	Kon
	NEL

160 ns

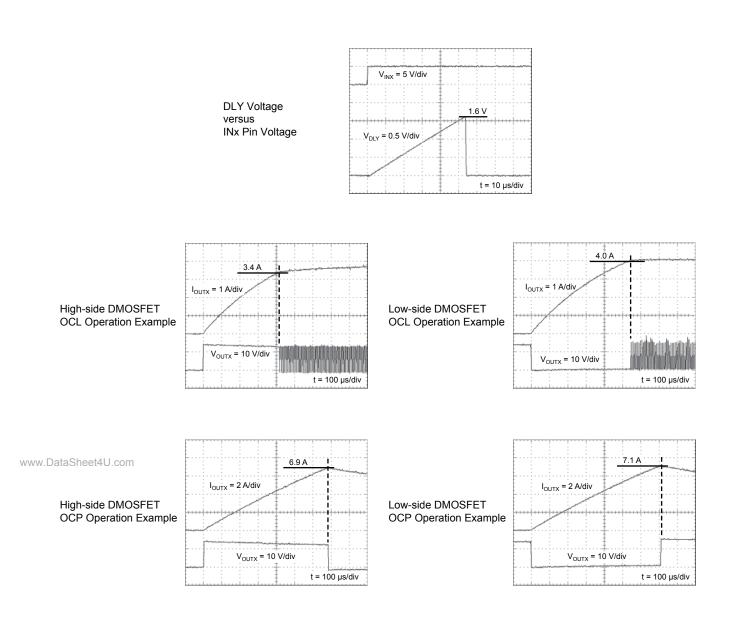


V_{OUTX} = 2 V/div

t = 100 ns/div

140 ns

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Protection Function Operation

Current Limitation and Overcurrent Protection

The overcurrent limit is adapted to each DMOSFET, and is activated when the drain current reaches 3 A typical. After that, it is followed by a 3 μ s typical off-time, and then it restarts automatically.

Overcurrent protection is activated when the drain current reaches 6 A typical within 3 μ s, as shown in figure 3. It shuts down the IC in a latch mode. Setting the DI pin to logic low level resets the internal logic circuit and releases the latch.

DIAG Pin and Open Load Detection Behavior

Open load detection does not operate until after the output voltage of OUT1 (V_{OUT1}) reaches about $V_{BB} - 2$ V. If an open load is detected, the DIAG signal goes high. The process of open load detection is shown in figure 4:

A. During this period, UVLO is activated and DIAG stays low.

B. If a filtering capacitor is used at the outputs, it causes a delay of open load detection. (Refer to figure 5 for the relationship of the delay versus the filtering capacitor value.)

C. The open load detection period starts functioning. Raising DI input above $V_{DI_{-}H}$ (threshold), that is, by activating the IC, clears the DIAG signal. Therefore, the open load condition must be checked before the time of that event.

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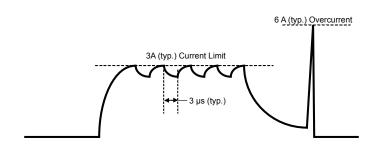


Figure 3. Behavior of Current Limitation and Overcurrent Protection function

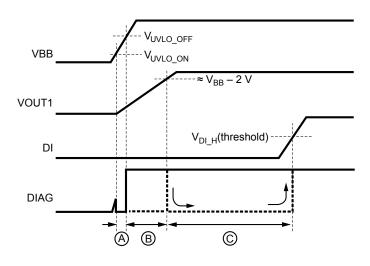
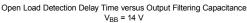


Figure 4. Open Load Detection



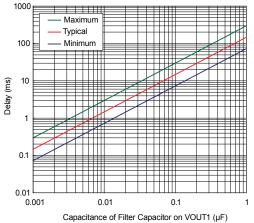


Figure 5. Delay to Open Load protection activation versus value of external capacitor on the output pins





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Open load detection during normal operation of the IC is done by checking the negative potential of the output.

Referring to figure 6, during normal operation, recirculation current causes the output to be below GND. The IC checks the output voltage during 2.5 μ s typical, just after the falling edge of the corresponding IN signal, and if it does not detect the negative potential, DIAG is asserted after the 2.5 μ s detection period. During the 2.5 μ s period, the DIAG pin is set to high because the internal circuit is reset during that period (see the arrows marked *A* in figure 6).

Open load detection operates differently during startup of the IC. The overcurrent limitation deactivated period occurs immediately after DI is asserted. Therefore, in order to repeat OCL deactivation, recycle DI.

During this period, overcurrent protection (OCP) is still active. (With regard to OCL delay, see also note 2 to the Electrical Characteristics table.)

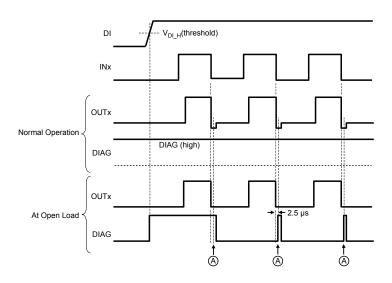


Figure 6. Open load detection in normal operation

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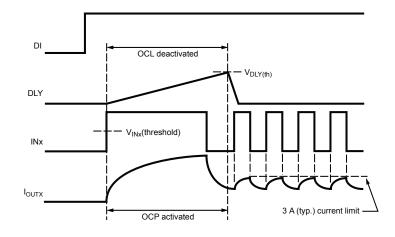


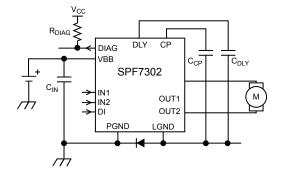
Figure 7. DLY pin effect at startup





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Application Information





C _{CP}	48 nF
C _{DLY}	0.1 µF
R _{DIAG}	3.3 kΩ

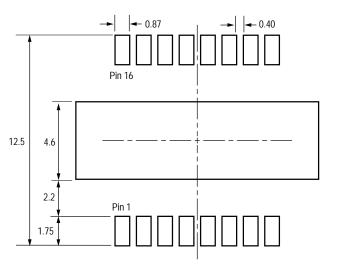


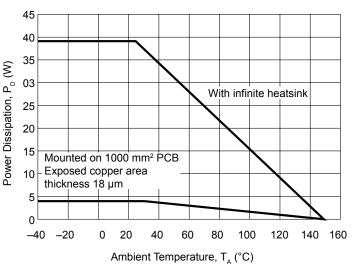
Figure 9. Recommended Solder Pad Layout, dimensions in mm





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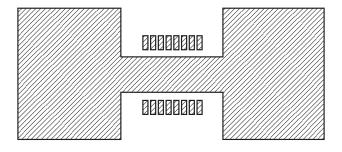


Figure 12. Test PCB Land Pattern www.DataSheet4U.com

Approximate power dissipation, P_D , in normal operation is calculated by equation 1, and the junction temperature, T_J , is estimated by equation 2 or 3. Figure 13 shows example data of ΔT_J versus P_D . Note: a final thermal evaluation should be done under actual application conditions, taking into account actual PCB and load conditions.

$$\begin{split} P_D &\approx V_{BB} \times I_{BB1} + \ (V_{satH} + V_{satL}) \times I_{OM} \times D_{ON} \\ &+ (V_{satL(H)} + V_F) \times I_{OM} \times D_{OFF} \end{split} \tag{1}$$

where:

 V_{BB} is the supply voltage (battery voltage),

 I_{BB1} is the circuit current during operation,

V_{satH} is the high-side saturation voltage,

V_{satL} is the low-side saturation voltage,

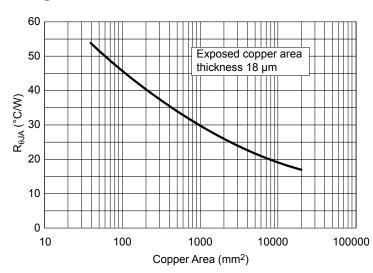


Figure 11. Thermal Resistance versus PCB Copper Area

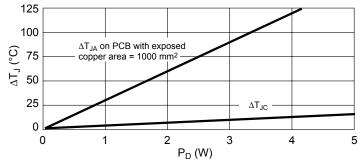


Figure 13. Thermal Performance

 V_{F} is the free wheeling diode forward voltage,

 I_{OM} is the motor current,

 D_{ON} is the IN1 and IN2 duty cycle (proportion on), and D_{OFF} is the IN1 and IN2 proportion off ($D_{ON} + D_{OFF} = 100\%$). To calculate T_J:

$$T_{\rm J} = R_{\rm \theta JA} \times P_{\rm D} + T_{\rm A} \tag{2}$$

$$T_{\rm J} = T_{\rm P} + R_{\rm \theta JC} (3.2^{\circ} {\rm C/W}) \times P_{\rm D}$$
(3)

where:

or

Thermal Design

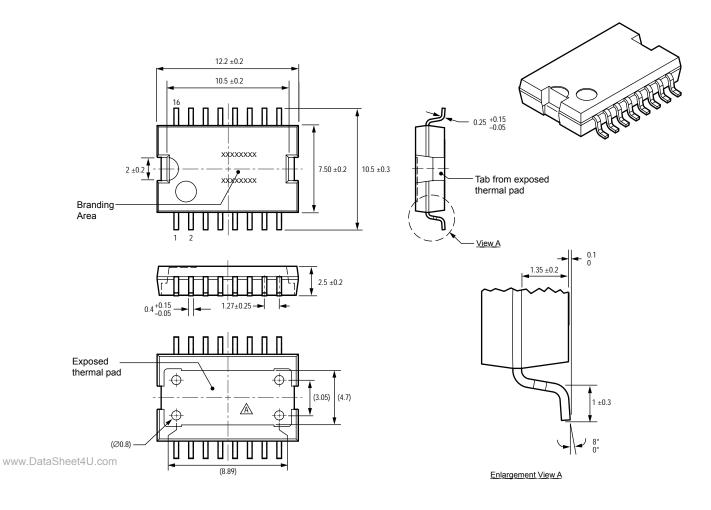
 $R_{\theta JA}$ can be obtained from figure 11, and T_P is the temperature at the exposed thermal pad of the device.





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Package Outline Drawing, 16 Pin HSOP



Package: HSOP-16

Dimensions in millimeters

Branding codes (exact appearance at manufacturer discretion): 1st line, type: SPF7302 2nd line, lot: YMDD Where: Y is the last digit of the year of manufacture M is the month (1 to 9, 0, N, D) DD is the date



Leadframe plating Pb-free. Device composition complies with the RoHS directive.





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WARNING — These devices are designed to be operated at lethal voltages and energy levels. Circuit designs that embody these components must conform with applicable safety requirements. Precautions must be taken to prevent accidental contact with power-line potentials. Do not connect grounded test equipment.

The use of an isolation transformer is recommended during circuit development and breadboarding.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

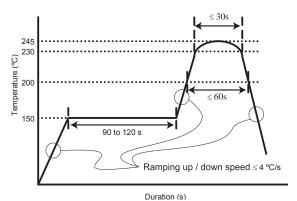
- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

Soldering

- When soldering the products, please be sure to minimize the working time, and any soldering iron should be kept at a distance from the body of the product.
- The number of reflow procedures is restricted to two only. Device reliability and appearance are guaranteed within the temperature profile below, after storage conditions of up to 168 hours at T_A = 85°C and RH = 85%.



Solder Reflow Profile

Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 $\mbox{M}\Omega$ of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in other to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.





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